

3GPP TSG RAN Meeting #95-e

RP-220541

Qualcomm

Electronic Meeting, March 17th - 23rd, 2022

Agenda Item 9.1.4.4

Views on Demod Enhancements

Qualcomm Incorporated

Introduction

- Performance enhancements have been defined in each NR release
- Demodulation improvements bring UE throughput gains and system capacity gains, and are important to guarantee a minimum system performance
- The topics presented in the next slides should be included in the Rel.18 demod enhancements work
 - Several topics were discussed in the RAN4 package e-mail discussion and are documented in RP-220022, we present the topics that should have highest priority
- Number of topics should be minimized because there is a lot of demodulation work expected in Rel.18
 - 8Rx and FR2 multi-panel requirements will have a lot of demod work
 - Items agreed in the RAN1/2/3 led Rel.18 package will also have demod scope

Advanced Receiver for MU-MIMO

- Definition of requirements assuming advanced receiver that can cancel the interference between different users in MU-MIMO
- Objective should be inline with the outcome of the RAN4 package email discussion (RP-220022)

ATP - Throughput Requirements with Link Adaptation

Continuation of the RAN5 led SI on Application layer throughput

- RAN5 led SI on Application Layer Throughput Requirements was just concluded
 - RAN4 part also finished and it was found feasible to introduce tests with “link adaptation”(variable rate channel)
- Objective is stable after the RAN4 package e-mail discussion (RP-220022)
- Objective should be included in the generic demod enhancements WI



Thank you

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